

/ Descriptions

1.0A UMB
1.0A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

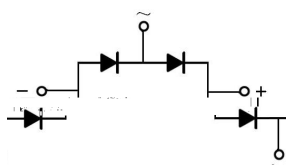
/ Features

Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V,
Forward Current:1.0A, Designed for Surface Mount Application. HF product.

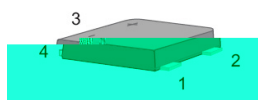
/ Applications

General purpose.

/ Equivalent Circuit

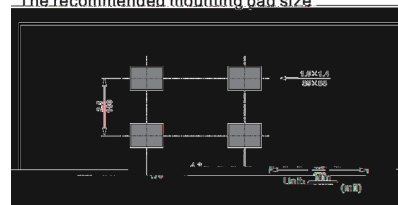


/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating						Unit
		UM1B-10	UM2B-10	UM4B-10	UM6B-10	UM8B-10	UM10B-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 115^\circ\text{C}$	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	$R_{\theta JA}$ $R_{\theta JC}$	85 25						$^{\circ}\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	$-55\sim 150$						

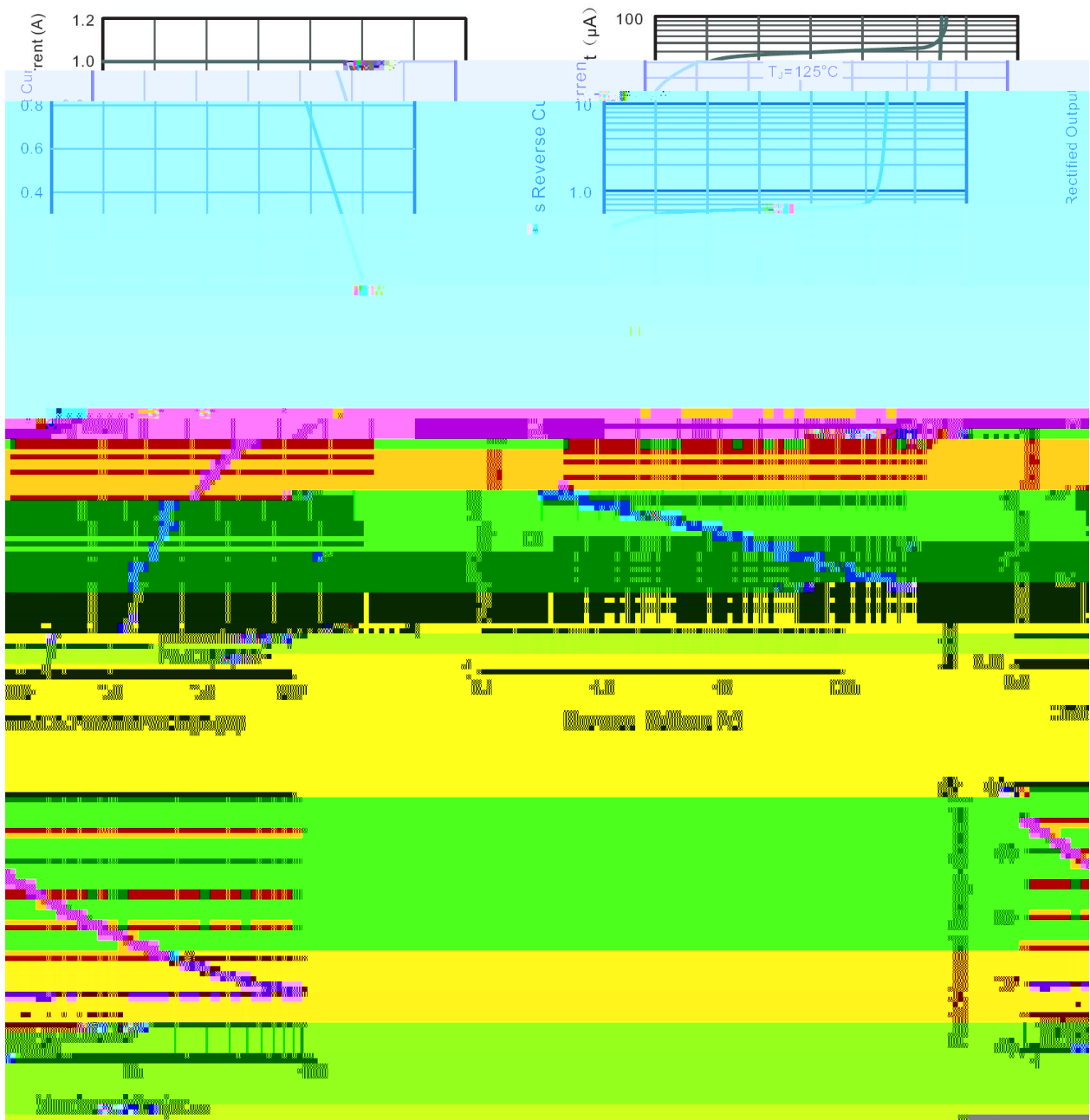
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5 x1.5 (3.81x3.81cm) copper pad areas.

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=1.0\text{A}$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25$	5.0	μA
		$T_a=125$	40	

/ Electrical Characteristic Curve



Marking

Type number	Marking code
UM1B-10	10U1
UM2B-10	10U2
UM4B-10	10U4
UM6B-10	10U6
UM8B-10	10U8
UM10B-10	10U10

/ Marking Instructions



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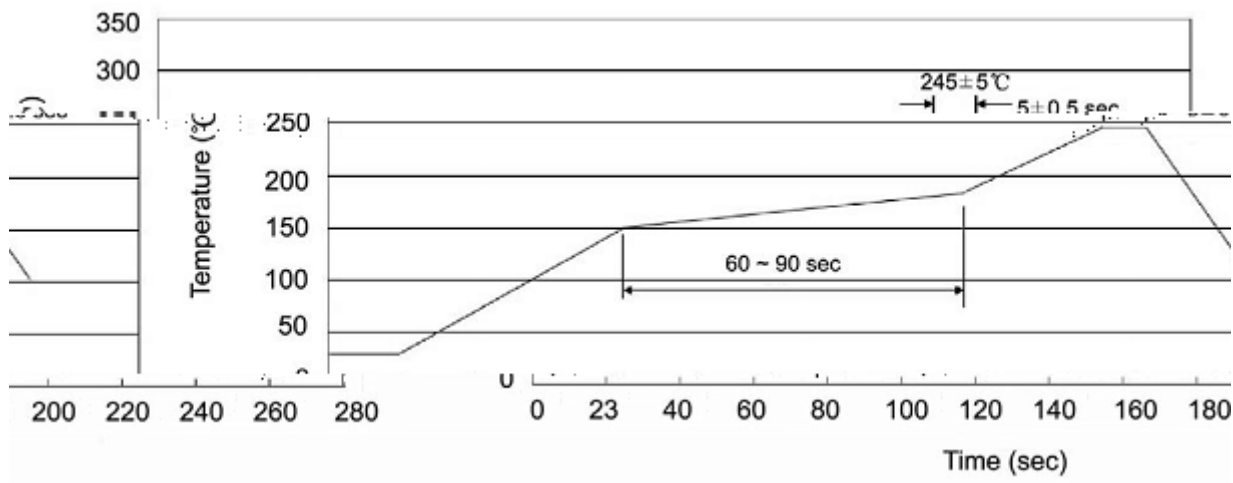
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Note:

Product Type Code

Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot
No Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
UMB	5000	2	10,000	5	50,000	13 16	340 × 340 × 40	350 × 350 × 230

/ Notices